

What is claimed is:

[Claim 1] 1. An electronic package with a passive component comprising:

a circuit carrier having a patterning circuit layer, said patterning circuit layer having at least a passive-component-pad set, said passive-component-pad set having a first pad and a second pad;
at least a passive component having a first electrode and a second electrode positioned over said first pad and said second pad, respectively; and
an anisotropic conductive layer arranged between said first electrode and said first pad and between said second electrode and said second pad.

[Claim 2] 2. The electronic package of claim 1, wherein said anisotropic conductive layer covers said circuit carrier between said first pad and said second pad.

[Claim 3] 3. The electronic package of claim 1, wherein said anisotropic conductive layer covers said first pad and said second pad.

[Claim 4] 4. The electronic package of claim 1, wherein said circuit carrier further includes a solder-mask layer having at least one opening exposing all of the upper surface of said first pad and all of the upper surface of said second pad.

[Claim 5] 5. The electronic package of claim 4, wherein there is no solder-mask layer formed between said first pad and said second pad.

[Claim 6] 6. The electronic package of claim 1, wherein said circuit carrier further includes a solder-mask layer having at least one opening exposing part of the upper surface of said first pad and part of the upper surface of said second pad.

[Claim 7] 7. The electronic package of claim 1, further comprising a molding compound encapsulating said passive component.

[Claim 8] 8. The electronic package of claim 1, wherein said passive component comprises a resistor, an inductor or a capacitor.

[Claim 9] 9. The electronic package of claim 1, wherein said anisotropic conductive layer is made of anisotropic conductive film (ACF) or anisotropic conductive paste (ACP).

[Claim 10] 10. The electronic package of claim 1, further comprising at least a chip electrically connected to said circuit carrier.

[Claim 11] 11. The electronic package of claim 10, wherein said chip is electrically connected to said circuit carrier using a wire-bonding technology or using a flip-chip bonding technology.

[Claim 12] 12. The electronic package of claim 1, further comprising multiple electrical contacts arranged on said circuit carrier.

[Claim 13] 13. The electronic package of claim 12, wherein said electrical contacts comprise pins or solder balls.

[Claim 14] 14. An electronic package with a passive component comprising:

a circuit carrier having at least a passive-component-pad set, said passive-component-pad set having multiple pads;
at least a passive component having multiple electrodes positioned over said pads of said circuit carrier, respectively; and
an anisotropic conductive layer arranged between said electrodes and said pads.

[Claim 15] 15. The electronic package of claim 14, wherein said anisotropic conductive layer covers said circuit carrier between said pads.

[Claim 16] 16. The electronic package of claim 14, wherein said anisotropic conductive layer covers said pads.

[Claim 17] 17. The electronic package of claim 14, wherein said circuit carrier further includes a solder-mask layer having at least one opening exposing all of the upper surfaces of said pads.

[Claim 18] 18. The electronic package of claim 17, wherein there is no solder-mask layer formed among said pads.

- [Claim 19] 19. The electronic package of claim 14, wherein said circuit carrier further includes a solder-mask layer having at least one opening exposing part of the upper surfaces of said pads.
- [Claim 20] 20. The electronic package of claim 14, further comprising a molding compound encapsulating said passive component.
- [Claim 21] 21. The electronic package of claim 14, wherein said passive component comprises a resistor, an inductor or a capacitor.
- [Claim 22] 22. The electronic package of claim 14, wherein said anisotropic conductive layer is made of anisotropic conductive film (ACF) or anisotropic conductive paste (ACP).
- [Claim 23] 23. The electronic package of claim 14, further comprising at least a chip electrically connected to said circuit carrier.
- [Claim 24] 24. The electronic package of claim 23, wherein said chip is electrically connected to said circuit carrier using a wire-bonding technology or using a flip-chip bonding technology.
- [Claim 25] 25. The electronic package of claim 14, further comprising multiple electrical contacts arranged on said circuit carrier.